Complementary Silicon Power Plastic Transistors

These devices are designed for low voltage, low-power, high-gain audio amplifier applications.

Features

- High DC Current Gain
- Low Collector-Emitter Saturation Voltage
- High Current-Gain Bandwidth Product
- Annular Construction for Low Leakage
- These Devices are Pb-Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CB}	25	Vdc
Emitter-Base Voltage	V _{EB}	8.0	Vdc
Collector Current – Continuous	I _C	5.0	Adc
Collector Current – Peak	I _{CM}	10	Adc
Base Current	I _B	1.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.12	W mW/°C
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 0.012	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

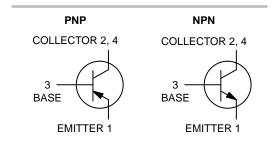
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.34	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.4	°C/W



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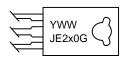
http://onsemi.com

5.0 AMPERES POWER TRANSISTORS COMPLEMENTARY SILICON 25 VOLTS, 15 WATTS





MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping
MJE200G	TO-225 (Pb-Free)	500 Units / Box
MJE210G	TO-225 (Pb-Free)	500 Units / Box
MJE210TG	TO-225 (Pb-Free)	500 Units / Box

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	-		•	
Collector–Emitter Sustaining Voltage (Note 1) $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{CEO(sus)}	25	-	Vdc
Collector Cutoff Current $(V_{CB} = 40 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 40 \text{ Vdc}, I_E = 0, T_J = 125^{\circ}\text{C})$	I _{CBO}	- -	100 100	nAdc μAdc
Emitter Cutoff Current (V _{BE} = 8.0 Vdc, I _C = 0)	I _{EBO}	_	100	nAdc
ON CHARACTERISTICS	<u> </u>			
DC Current Gain (Note 1) $(I_C = 500 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 2.0 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 5.0 \text{ Adc}, V_{CE} = 2.0 \text{ Vdc})$	h _{FE}	70 45 10	- 180 -	-
Collector–Emitter Saturation Voltage (Note 1) ($I_C = 500 \text{ mAdc}$, $I_B = 50 \text{ mAdc}$) ($I_C = 2.0 \text{ Adc}$, $I_B = 200 \text{ mAdc}$) ($I_C = 5.0 \text{ Adc}$, $I_B = 1.0 \text{ Adc}$)	V _{CE(sat)}	- - -	0.3 0.75 1.8	Vdc
Base–Emitter Saturation Voltage (Note 1) (I _C = 5.0 Adc, I _B = 1.0 Adc)	V _{BE(sat)}	-	2.5	Vdc
Base–Emitter On Voltage (Note 1) (I _C = 2.0 Adc, V _{CE} = 1.0 Vdc)	V _{BE(on)}	_	1.6	Vdc
DYNAMIC CHARACTERISTICS			•	•
Current–Gain – Bandwidth Product (Note 2) (I _C = 100 mAdc, V _{CE} = 10 Vdc, f _{test} = 10 MHz)	f _T	65	-	MHz
Output Capacitance $(V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 0.1 \text{ MHz})$ MJE200G MJE210G	C _{ob}	<u>-</u>	80 120	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test condition performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \approx 2.0%. 2. $f_T = |h_{fe}| \bullet f_{test}$.

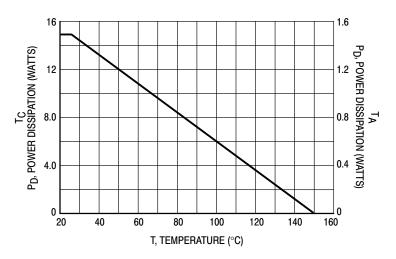
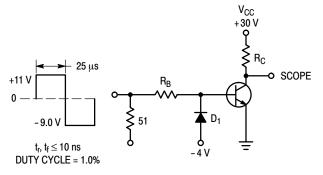


Figure 1. Power Derating



 R_B and R_C VARIED TO OBTAIN DESIRED CURRENT LEVELS D_1 MUST BE FAST RECOVERY TYPE, e.g.: 1N5825 USED ABOVE $I_B\approx 100$ mA MSD6100 USED BELOW $I_B\approx 100$ mA

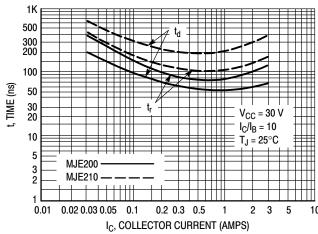


Figure 3. Turn-On Time

Figure 2. Switching Time Test Circuit

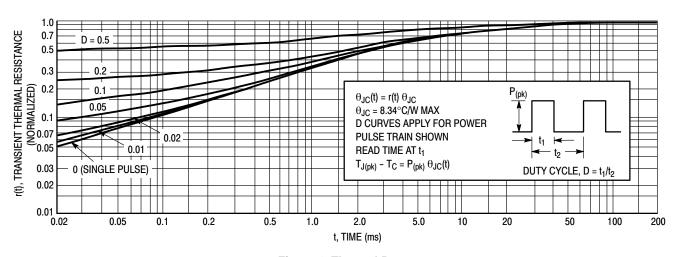


Figure 4. Thermal Response

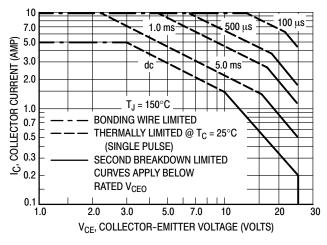


Figure 5. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)} = 150^{\circ}C$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

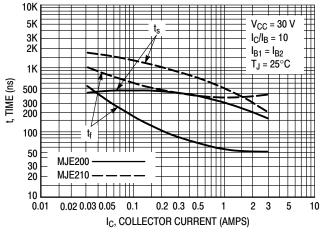


Figure 6. Turn-Off Time

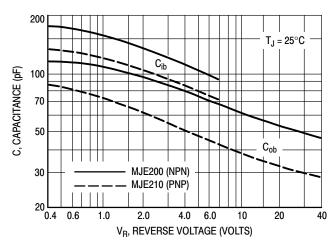
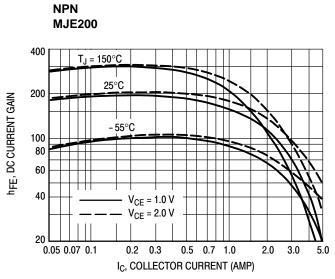
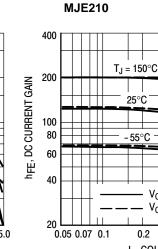


Figure 7. Capacitance

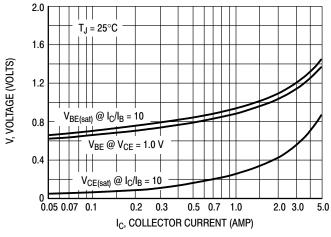


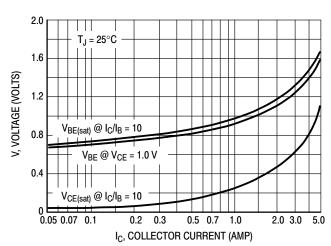


PNP

25°C

Figure 8. DC Current Gain





 $V_{CE} = 1.0 V$

 $V_{CE} = 2.0 V$

0.2 0.3

0.5 0.7 1.0

IC, COLLECTOR CURRENT (AMP)

2.0

3.0

5.0

Figure 9. "On" Voltage

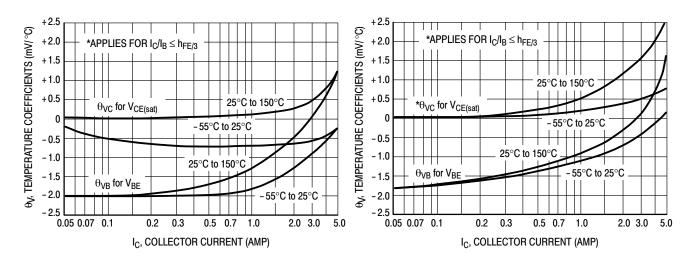
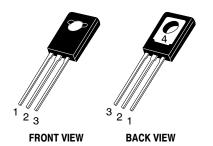


Figure 10. Temperature Coefficients

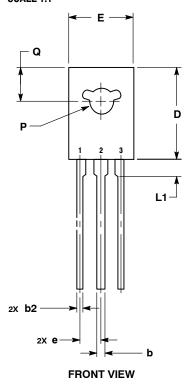
MECHANICAL CASE OUTLINE

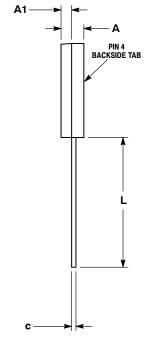


TO-225 CASE 77-09 **ISSUE AD**

DATE 25 MAR 2015

SCALE 1:1



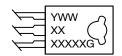


SIDE VIEW

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. NUMBER AND SHAPE OF LUGS OPTIONAL.

	MILLIMETERS				
DIM	MIN MAX				
Α	2.40	3.00			
A1	1.00	1.50			
b	0.60	0.90			
b2	0.51	0.88			
С	0.39	0.63			
D	10.60	11.10			
E	7.40	7.80			
е	2.04	2.54			
L	14.50	16.63			
L1	1.27	2.54			
Р	2.90	3.30			
D	3.80	4.20			

GENERIC MARKING DIAGRAM*



= Year

WW = Work Week XXXXX = Device Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

,		2., 4.	CATHODE ANODE GATE	2., 4.	BASE COLLECTOR EMITTER	,		,	MT 1 MT 2 GATE
2., 4	. CATHODE I. GATE		MT 1 GATE	2., 4.	SOURCE GATE	STYLE 9: PIN 1. 2., 4.	GATE DRAIN	2., 4.	SOURCE DRAIN
	B. ANODE	3.	MT 2	3.	DRAIN	3.	SOURCE	3.	GATE

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